



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Tee Onn Chong et al.

Title: ELECTRONIC PACKAGE WITH HIGH DENSITY INTERCONNECT AND ASSOCIATED METHODS

Docket No.: 884.419US1

Filed: May 15, 2001

Examiner: John B. Vigushin

Commissioner for Patents  
Washington, D.C. 20231

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19-0743	
FEE CODE	VALUE FURNISHED
1202	180
1201	168

Serial No.: 09/858,238

Due Date: October 18, 2002

Group Art Unit: 2827

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We are transmitting herewith the following attached items (as indicated with an "X"):

- ☒ A return postcard.
- ☒ An Amendment and Response Under 37 CFR 1.111 (20 Pages).
- ☒ Clean Version of Pending Claims (7 pgs.).
- ☒ Clean Version of Amended Specification Paragraphs (5 pgs.).

Please consider this a **PETITION FOR EXTENSION OF TIME** for sufficient number of months to enter these papers and please charge any additional required fees or credit overpayment to Deposit Account No. 19-0743.

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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231, on this 11 day of October, 2002.

Jane E. Brockschink  
Name

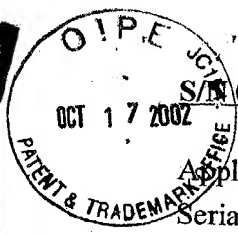
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(GENERAL)



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**PATENT**

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Title: ELECTRONIC PACKAGE WITH HIGH DENSITY INTERCONNECT AND ASSOCIATED METHODS

#3/10

Am Jt  
JAC Miller

**AMENDMENT AND RESPONSE UNDER 37 CFR §1.111**

11/12/02

Commissioner for Patents  
Washington, D.C. 20231

Applicants have reviewed the Office Action mailed on July 18, 2002. Please amend the above-identified patent application as follows.

**IN THE SPECIFICATION**

Please make the paragraph substitutions indicated in the appendix entitled "Clean Version of Amended Specification Paragraphs". The specific changes incorporated in the substitute paragraphs are shown in the following marked-up versions of the original paragraphs. The subtitle beginning on page 1, line 5 is amended as follows:

Technical Field [of the Invention]

The paragraph beginning on page 1, line 7 is amended as follows:

Embodiments of the [The] present invention relate [relates] generally to electronics packaging[.] and, more particularly, [More particularly, the present invention relates] to an electronic package that includes an integrated circuit die or an integrated circuit package coupled to a substrate with a high density interconnect, and to manufacturing methods related thereto.

The subtitle beginning on page 1, line 12 is amended as follows:

Background Information [of the Invention]

The paragraph beginning on page 4, line 29 is amended as follows:

In the following detailed description of embodiments of the invention, reference is made to the accompanying drawings which form a part hereof, and in which is shown by way of

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